



#### N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
60V	5.0Ω @ V <sub>GS</sub> = 10V	240mA
000	7.5Ω @ V <sub>GS</sub> = 5V	190mA

### **Description**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- Motor Control
- Power Management Functions
- Backlighting

### **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

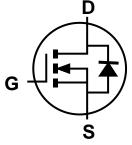
#### **Mechanical Data**

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding
   Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Alloy 42
   Leadframe. Solderable per MIL-STD-202, Method 208 
   3
- Weight: 0.006 grams (Approximate)

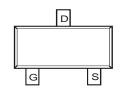








**Equivalent Circuit** 



Top View

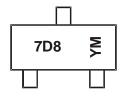
### Ordering Information (Note 4)

Part Number	Case	Packaging
DMN67D8LW-7	SOT323	3000/Tape & Reel
DMN67D8LW-13	SOT323	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**



7D8= Product Type Marking Code YM or  $\overline{Y}$ M = Date Code Marking Y or  $\overline{Y}$  = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025
Code	В	С	D	E	F	G	Н		J	K	L	M
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			$V_{DSS}$	60	V
Gate-Source Voltage	V <sub>GSS</sub>	±30	V		
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	ΙD	240 180	mA
Maximum Continuous Body Diode Forward Current	I <sub>S</sub>	0.5	Α		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	6) (Note 6)	)	I <sub>DM</sub>	0.8	Α

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		$P_{D}$	320	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	398	°C/W
Total Power Dissipation (Note 6)		P <sub>D</sub>	470	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	273	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

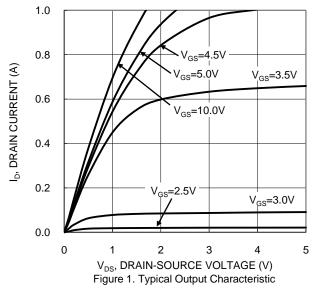
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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	1.0	μΑ	$V_{DS} = 60V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>		_	±100	nΑ	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0	_	2.5	٧	$V_{DS} = 10V, I_D = 250\mu A$
Static Drain-Source On-Resistance	D- avan		1.5	5.0	Ω	$V_{GS} = 10V, I_D = 0.5A$
Static Drain-Source On-Nesistance	R <sub>DS(ON)</sub>		3.2	7.5	32	$V_{GS} = 5V, I_D = 0.05A$
Forward Transfer Admittance	Y <sub>fs</sub>	80	_	_	mS	$V_{DS} = 10V, I_D = 0.2A$
Diode Forward Voltage	$V_{SD}$		0.78	1.5	>	$V_{GS} = 0V, I_{S} = 115mA$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	$C_{iss}$	-	22	_	pF	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\
Output Capacitance	Coss		4.1	_	рF	$V_{DS} = 25V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	$C_{rss}$		2.5	_	pF	1 – 1.01011 12
Gate Resistance	$R_{g}$		120	_	Ω	$f = 1.0MHz$ , $V_{GS} = 0V$ , $V_{DS} = 0V$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$		361	_	рС	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg		821		рС	$V_{GS} = 4.5V, V_{DS} = 10V,$
Gate-Source Charge	$Q_{gs}$		162		рС	$I_D = 250 \text{mA}$
Gate-Drain Charge	$Q_{gd}$		116	_	рC	
Turn-On Delay Time	t <sub>D(ON)</sub>	l	2.8	_	ns	
Turn-On Rise Time	t <sub>R</sub>		3.0	_	ns	$V_{DD} = 30V, I_D = 0.2A,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	l	7.6	_	ns	$R_L = 150\Omega$ , $V_{GS} = 10V$ , $R_G = 25\Omega$
Turn-Off Fall Time	t <sub>F</sub>		5.6	_	ns	

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout
  - 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided. 7. Short duration pulse test used to minimize self-heating effect.

  - 8. Guaranteed by design. Not subject to product testing.





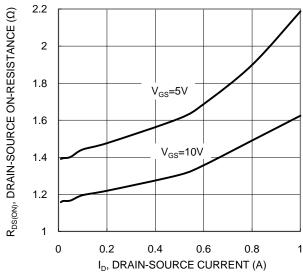


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

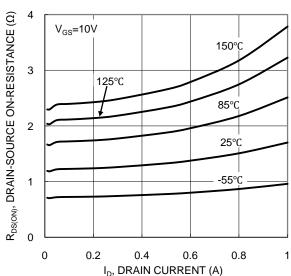
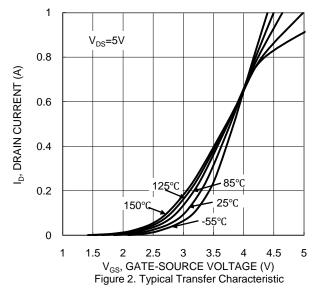
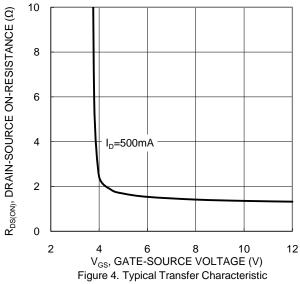


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





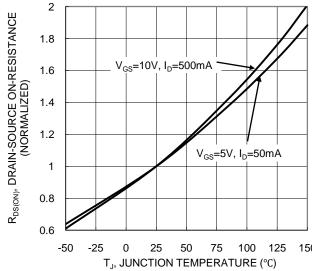


Figure 6. On-Resistance Variation with Junction
Temperature



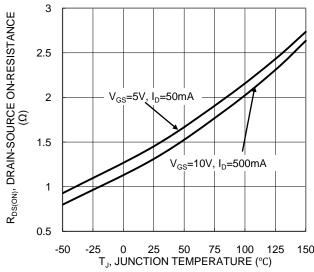
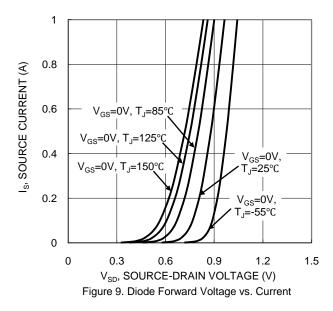
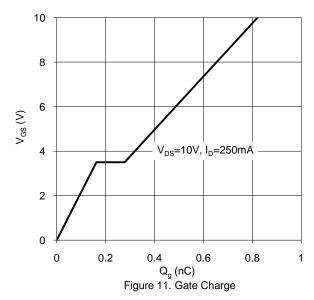


Figure 7. On-Resistance Variation with Junction Temperature





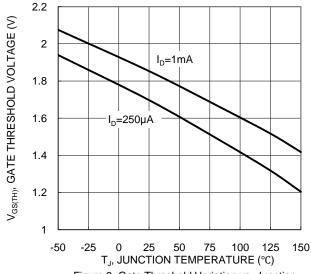
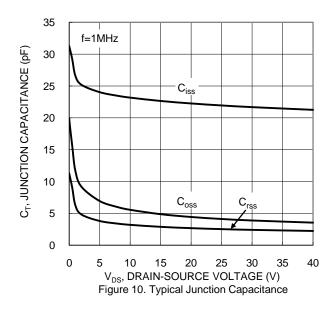
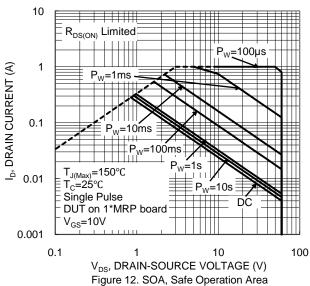
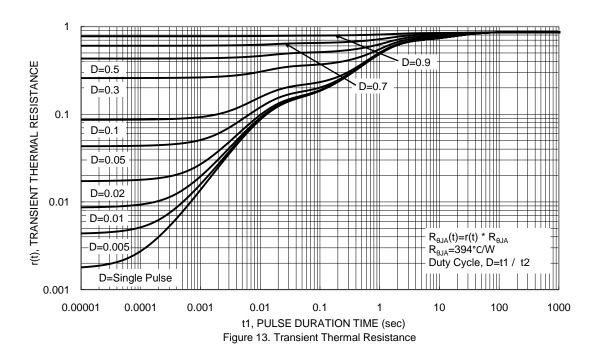


Figure 8. Gate Threshold Variation vs. Junction Temperature



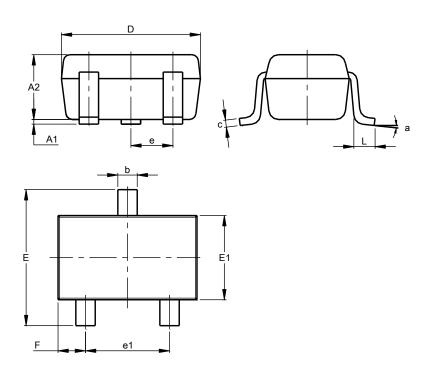






## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

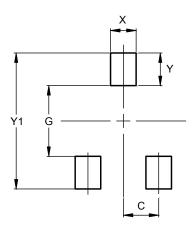


SOT323							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.25	0.40	0.30				
С	0.10	0.18	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	(	).650 B	SC				
e1	1.20	1.40	1.30				
F	0.375	0.475	0.425				
L	0.25	0.40	0.30				
а	a 8°						
All Dimensions in mm							



### Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	0.650		
G	1.300		
Х	0.470		
Υ	0.600		
Y1	2.500		

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